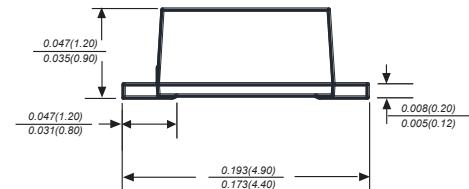
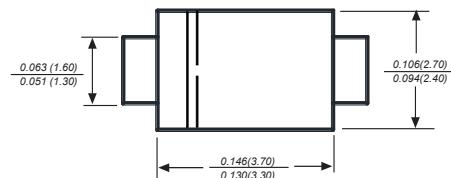




SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
- ◆ 260°C/10 seconds at terminals
- Glass passivated chip junction

SMAF ROHS
COMPLIANT

Dimensions in inches and (millimeters)

Mechanical Data

Case : JEDEC SMAF Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0018 ounce, 0.064 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MDD ES3AF	MDD ES3BF	MDD ES3CF	MDD ES3DF	MDD ES3EF	MDD ES3GF	MDD ES3JF	UNITS		
Marking Code											
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	600	V		
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V		
Maximum DC blocking voltage	V_{DC}	50	100	150	200	300	400	600	V		
Maximum average forward rectified current at $T_L=55^\circ\text{C}$	$I_{(AV)}$	3.0							A		
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50							A		
Maximum instantaneous forward voltage at 3.0A	V_F	0.95			1.25		1.7	V			
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	5.0 200							uA		
Maximum reverse recovery time (NOTE 1)	t_{rr}	35							ns		
Typical junction capacitance (NOTE 2)	C_J	60.0							pF		
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	40.0							°C/W		
Operating junction and storage temperature range	T_J, T_{STG}	-50 to +150							°C		

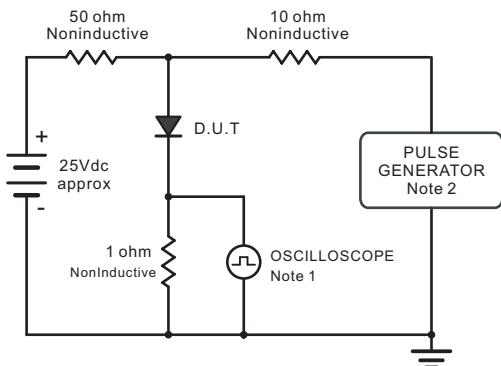
Note: 1. Reverse recovery condition $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{rr}=0.25\text{A}$

2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

3. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas



Ratings And Characteristic Curves



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm,22pF.
2. Ries Time =10ns, max.
Source Impedance = 50 ohms.

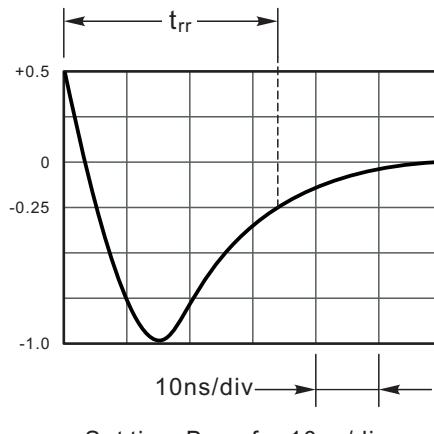


Fig.2 Maximum Average Forward Current Rating

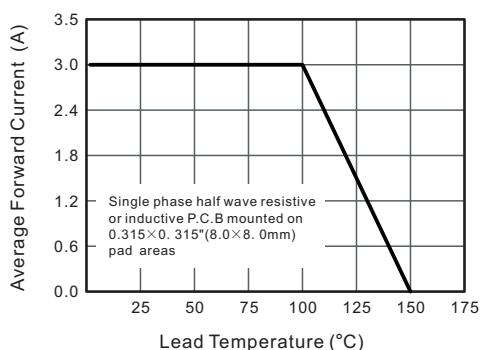


Fig.3 Typical Reverse Characteristics

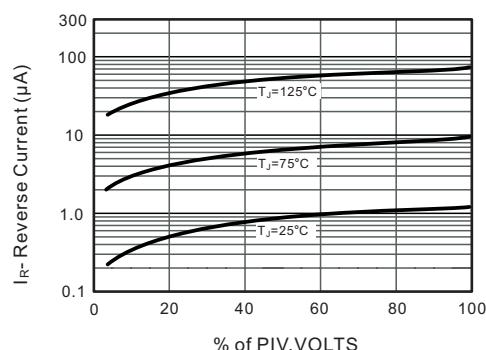


Fig.4 Typical Forward Characteristics

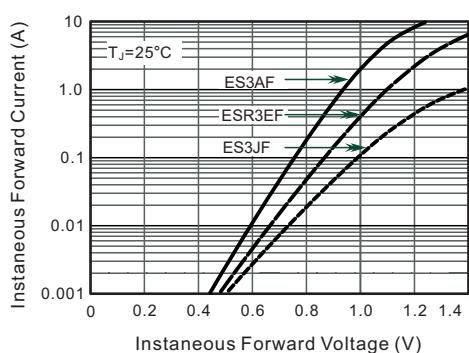
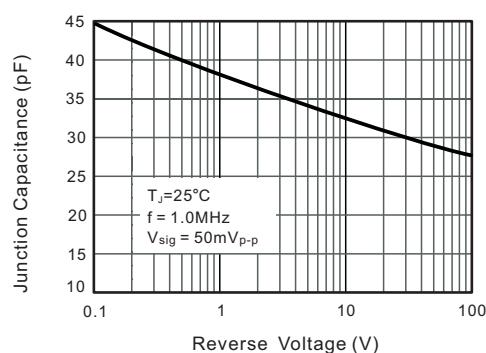


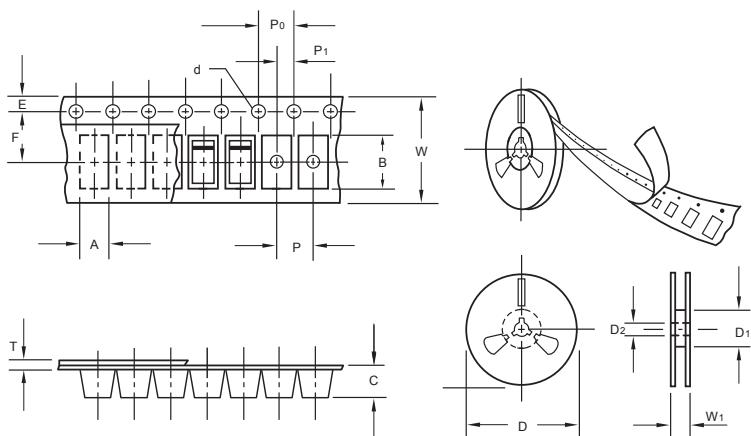
Fig.5 Typical Junction Capacitance



The curve above is for reference only.



Packing information



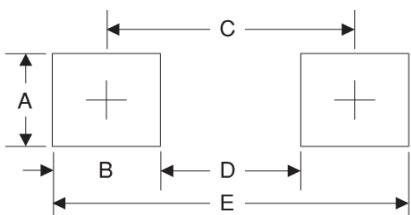
Item	Symbol	Tolerance	SMAF
Carrier width	A	0.1	2.80
Carrier length	B	0.1	4.75
Carrier depth	C	0.1	1.42
Sprocket hole	d	0.05	1.50
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	54.40
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.05
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	8.00
Reel width	W ₁	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMAF	7"	3,000	4.0	6,000	210*208*203	178	400*265*400	120,000	10.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.8	0.071
B	1.6	0.063
C	3.8	0.150
D	2.2	0.087
E	5.4	0.213